

**pASIC 2
HIGHLIGHTS**

*... 3,000
usable ASIC gates,
118 I/O pins*

**QL2003
Block Diagram**

**192
Logic
Cells**



☒ Ultimate Verilog/VHDL Silicon Solution

- Abundant, high-speed interconnect eliminates manual routing
- Flexible logic cell provides high efficiency *and* performance
- Design tools produce fast, efficient Verilog/VHDL synthesis

☒ Speed, Density, Low Cost and Flexibility in One Device

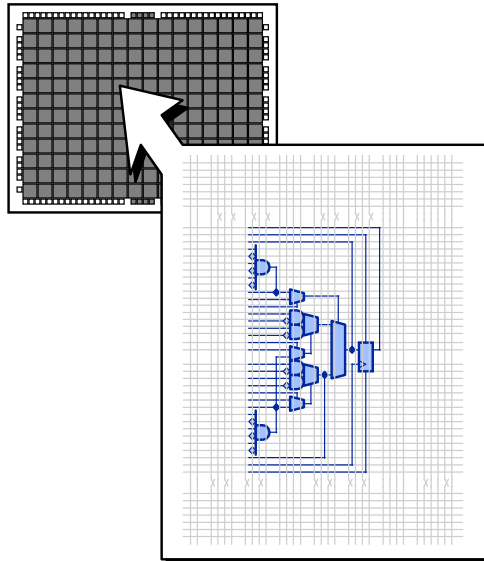
- 16-bit counter speeds exceeding 200 MHz
- 3,000 usable ASIC gates, 5,000 usable PLD gates, 118 I/Os
- 3-layer metal ViaLink[®] process for small die sizes
- 100% routable and pin-out maintainable

☒ Advanced Logic Cell and I/O Capabilities

- Complex functions (up to 16 inputs) in a single logic cell
- High synthesis gate utilization from logic cell fragments
- Full IEEE Standard JTAG boundary scan capability
- Individually-controlled input/feedback registers and OEs on all I/O pins

☒ Other Important Family Features

- 3.3V and 5.0V operation with low standby power
- I/O pin-compatibility between different devices in the same packages
- PCI compliant (at 5.0V), full speed 33 MHz implementations
- High design security provided by security fuses





PRODUCT SUMMARY

The QL2003 is a 3,000 usable ASIC gate, 5,000 usable PLD gate member of the pASIC 2 family of FPGAs. pASIC 2 FPGAs employ a unique combination of architecture, technology, and software tools to provide high speed, high usable density, low price, and flexibility in the same devices. The flexibility and speed make pASIC 2 devices an efficient and high performance silicon solution for designs described using HDLs such as Verilog and VHDL, as well as schematics.

The QL2003 contains 192 logic cells. With 118 maximum I/Os, the QL2003 is available in 84-PLCC, 100-pin TQFP and 144-pin TQFP packages.

Software support for the complete pASIC families, including the QL2003, is available through three basic packages. The turnkey QuickWorks[®] package provides the most complete FPGA software solution from design entry to logic synthesis (by Synplicity, Inc.), to place and route, to simulation. The QuickTools[™] and QuickChip[™] packages provide a solution for designers who use Cadence, Mentor, Synopsys, Viewlogic, Veribest, or other third-party tools for design entry, synthesis, or simulation.

FEATURES

☒ Total of 118 I/O Pins

- 110 bidirectional input/output pins, PCI-compliant at 5.0V in -1/-2 speed grades
- 4 high-drive input-only pins
- 4 high-drive input/distributed network pins

☒ Four Low-Skew (less than 0.5ns) Distributed Networks

- Two array networks available to logic cell flip-flop clock, set, and reset - each driven by an input-only pin
- Two global clock/control networks available to F1 logic input, and logic cell flip-flop clock, set, reset; input and I/O register clock, reset, enable; and output enable controls - each driven by an input-only pin, or any input or I/O pin, or any logic cell output or I/O cell feedback

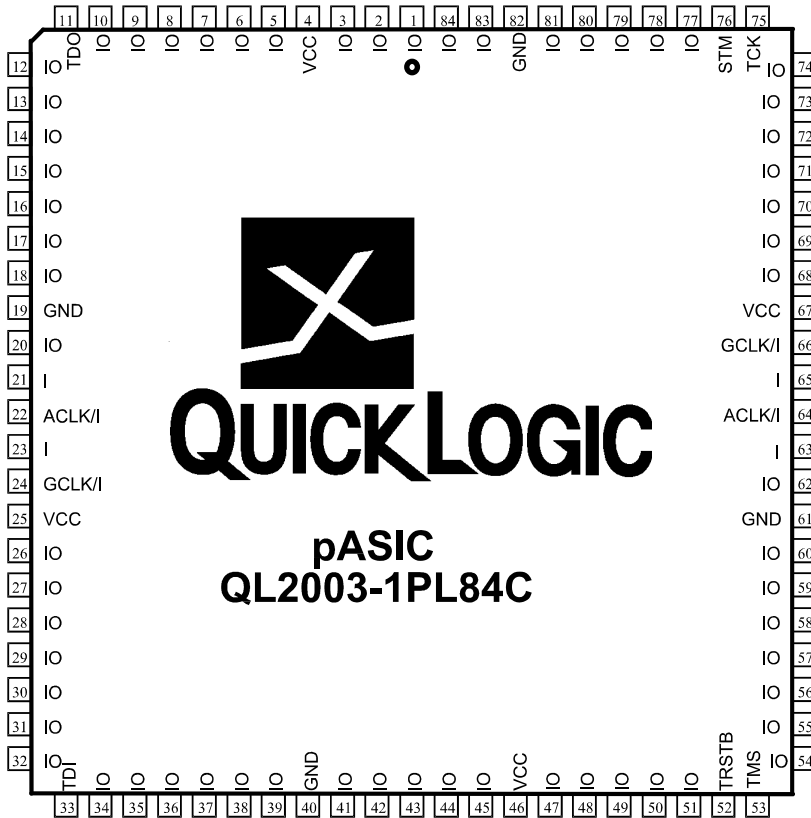
☒ High Performance

- Input + logic cell + output delays under 6 ns
- Datapath speeds exceeding 225 MHz
- Counter speeds over 200 MHz



PINOUT DIAGRAM

84-PIN PLCC

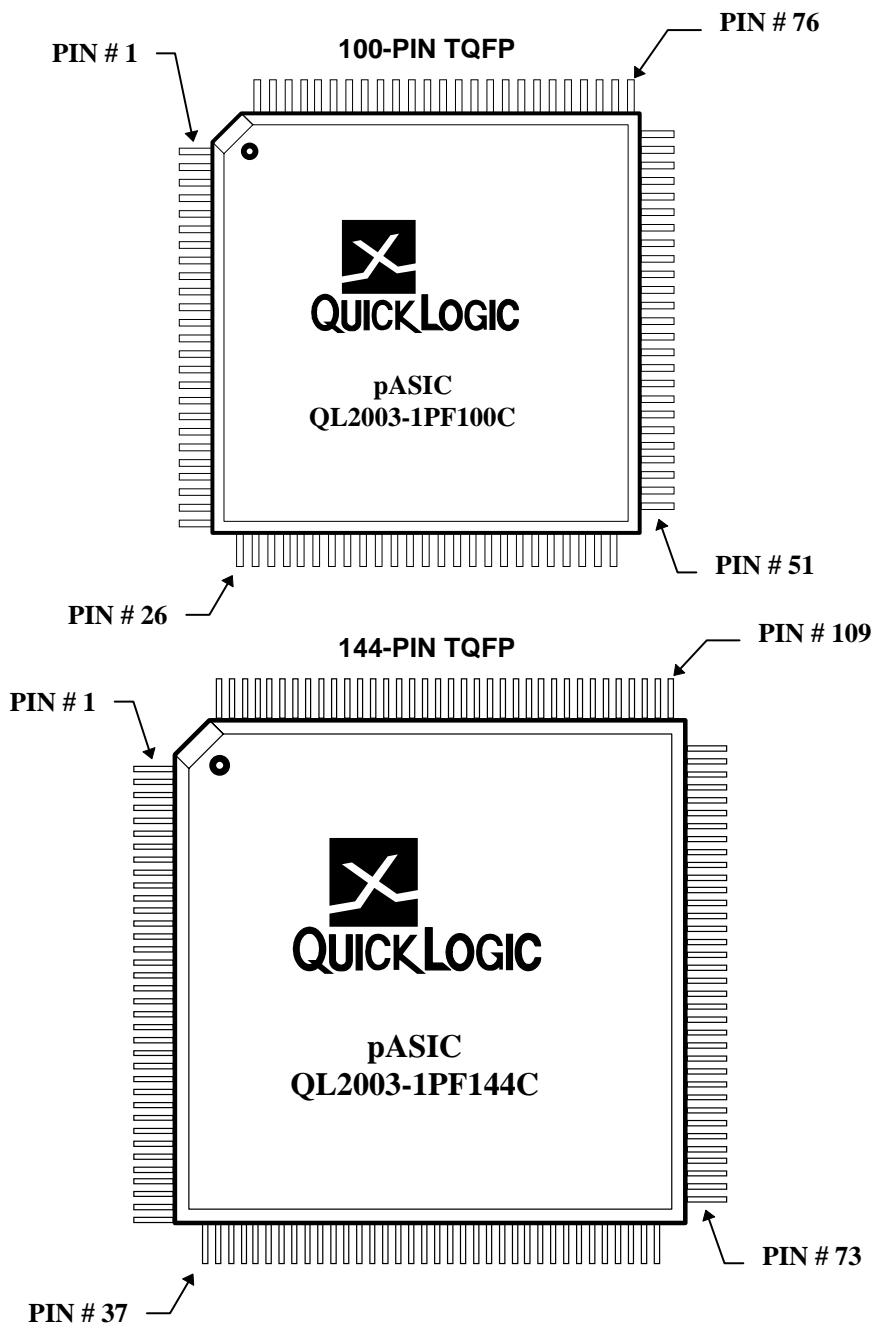


pASIC
QL2003-1PL84C

3
pASIC 2



PINOUT DIAGRAMS





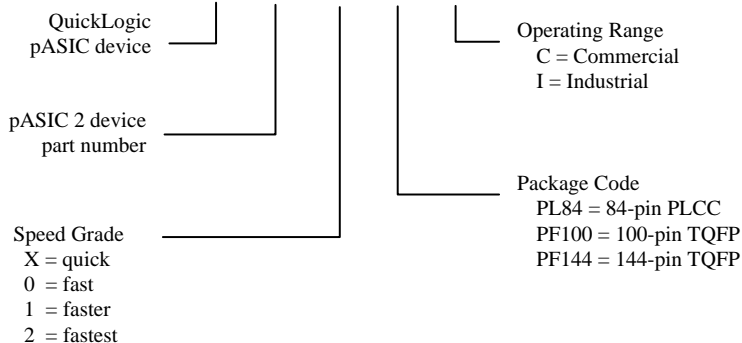
100 and 144 TQFP Pinout Table

144 TQFP	100 TQFP	Function	144 TQFP	100 TQFP	Function	144 TQFP	100 TQFP	Function	144 TQFP	100 TQFP	Function	144 TQFP	100 TQFP	Function
1	2	I/O	30	NC	GND	59	NC	I/O	88	60	I/O	116	82	I/O
2	NC	I/O	31	NC	I/O	60	43	I/O	89	61	I	117	83	I/O
3	3	I/O	32	22	I/O	61	44	I/O	90	62	ACLK / I	118	NC	I/O
4	4	I/O	33	NC	I/O	62	45	I/O	91	63	VCC	119	84	I/O
5	NC	I/O	34	23	I/O	63	NC	I/O	92	64	I	120	NC	I/O
6	5	I/O	35	NC	I/O	64	NC	I/O	93	65	GCLK / I	121	NC	I/O
7	NC	VCC	36	24	I/O	65	46	I/O	94	66	VCC	122	85	GND
8	6	I/O	37	25	I/O	66	NC	GND	95	67	I/O	123	NC	I/O
9	NC	I/O	38	26	TDI	67	NC	I/O	96	NC	I/O	124	86	I/O
10	7	I/O	39	27	I/O	68	NC	I/O	NC	68	I/O	125	87	I/O
11	NC	I/O	40	28	I/O	69	47	I/O	97	NC	I/O	126	88	GND
12	NC	I/O	41	29	I/O	70	48	I/O	98	69	I/O	127	89	I/O
13	8	I/O	42	NC	VCC	71	49	TRSTB	99	NC	I/O	128	90	I/O
14	NC	I/O	43	30	I/O	72	50	TMS	100	70	I/O	129	91	I/O
15	9	GND	44	31	I/O	73	51	I/O	101	71	I/O	130	92	VCC
16	10	I/O	45	NC	I/O	74	52	I/O	102	NC	GND	131	NC	I/O
17	11	I	46	32	I/O	75	53	I/O	103	NC	I/O	132	93	I/O
18	12	ACLK / I	47	33	I/O	76	54	I/O	104	72	I/O	133	NC	I/O
19	13	VCC	48	NC	I/O	77	55	I/O	105	NC	I/O	134	94	I/O
20	14	I	49	34	I/O	78	NC	I/O	106	73	I/O	135	NC	I/O
21	15	GCLK / I	50	35	GND	79	NC	VCC	107	74	I/O	136	NC	I/O
22	16	VCC	51	36	I/O	80	NC	I/O	108	75	I/O	137	95	I/O
23	17	I/O	52	NC	I/O	81	56	I/O	109	76	TCK	138	NC	GND
24	18	I/O	53	37	I/O	82	NC	I/O	110	77	STM	139	96	I/O
25	NC	I/O	54	38	GND	83	57	I/O	111	78	I/O	140	97	I/O
26	19	I/O	55	39	I/O	84	NC	I/O	112	79	I/O	141	98	I/O
27	NC	I/O	56	40	I/O	85	58	I/O	113	80	I/O	142	99	I/O
28	20	I/O	57	41	I/O	86	NC	I/O	114	NC	VCC	143	100	TDO
29	21	I/O	58	42	VCC	87	59	GND	115	81	I/O	144	1	I/O

3
PASIC 2

**PIN DESCRIPTIONS**

Pin	Function	Description
TDI	Test Data In for JTAG	Hold HIGH during normal operation. Connect to VCC if not used for JTAG.
TRSTB	Active low Reset for JTAG	Hold LOW during normal operation. Connect to ground if not used for JTAG.
TMS	Test Mode Select for JTAG	Hold HIGH during normal operation. Connect to VCC if not used for JTAG.
TCK	Test Clock for JTAG	Hold HIGH or LOW during normal operation. Connect to VCC or ground if not used for JTAG.
TDO	Test data out for JTAG	Output that must be left unconnected if not used for JTAG.
STM	Special Test Mode	Must be grounded during normal operation.
I/ACLK	High-drive input and/or array network driver	Can be configured as either or both.
I/GCLK	High-drive input and/or global network driver	Can be configured as either or both.
I	High-drive input	Use for input signals with high fanout.
I/O	Input/Output pin	Can be configured as an input and/or output.
VCC	Power supply pin	Connect to 3.3V supply.
GND	Ground pin	Connect to ground.

ORDERING INFORMATION**QL 2003 - 1 PF100 C**



ABSOLUTE MAXIMUM RATINGS

Supply Voltage -0.5 to 7.0V
 Input Voltage -0.5 to VCC +0.5V
 ESD Pad Protection ±2000V
 DC Input Current ±20 mA
 Latch-up Immunity ±200 mA

Storage Temperature..... -65°C to + 150°C
 Lead Temperature 300°C

5 Volt OPERATING RANGE

Symbol	Parameter	Industrial		Commercial		Unit	
		Min	Max	Min	Max		
VCC	Supply Voltage	4.5	5.5	4.75	5.25	V	
TA	Ambient Temperature	-40	85	0	70	°C	
TC	Case Temperature					°C	
K	Delay Factor	-X Speed Grade	0.4	2.75	0.46	2.55	
		-0 Speed Grade	0.4	2.00	0.46	1.85	
		-1 Speed Grade	0.4	1.61	0.46	1.50	
		-2 Speed Grade	0.4	1.35	0.46	1.25	

DC CHARACTERISTICS over 5V operating range

Symbol	Parameter	Conditions	Min	Max	Unit
VIH	Input HIGH Voltage		2.0		V
VIL	Input LOW Voltage			0.8	V
VOH	Output HIGH Voltage	IOH = -4 mA	3.7		V
		IOH = -24 mA/-16 mA [1]	2.4		V
		IOH = -10 µA	VCC-0.1		V
VOL	Output LOW Voltage	IOL = 24 mA/16 mA [1]		0.45	V
		IOL = 10 µA		0.1	V
II	Input Leakage Current	VI = VCC or GND	-10	10	µA
IOZ	3-State Output Leakage Current	VI = VCC or GND	-10	10	µA
CI	Input Capacitance [2]			10	pF
IOS	Output Short Circuit Current [3]	VO = GND	-15	-120	mA
		VO = VCC	40	210	mA
ICC	D.C. Supply Current [4]	VI, VIO = VCC or GND	2 (typ)	10	mA

Notes:

- [1] -24 mA IOH and 24 mA IOL apply only to -1/-2 commercial grade devices. These speed grades are also PCI-compliant. All other devices have -16 mA IOH and 16 mA IOL specifications.
- [2] Capacitance is sample tested only.
- [3] Only one output at a time. Duration should not exceed 30 seconds.
- [4] For -0/-1/-2 commercial grade devices only. Maximum ICC is 20 mA for -X commercial grade devices and 15mA for all industrial grade devices. For AC conditions, contact QuickLogic customer engineering.



3.3 Volt OPERATING RANGE

Symbol	Parameter	Industrial		Commercial		Unit	
		Min	Max	Min	Max		
VCC	Supply Voltage	3.0	3.6	3.0	3.6	V	
TA	Ambient Temperature	-40	85	0	70	°C	
K	Delay Factor	-0 Speed Grade	0.56	2.74	0.61	2.65	
		-1 Speed Grade	0.56	2.21	0.61	2.14	
		-2 Speed Grade	0.56	1.85	0.61	1.79	

DC CHARACTERISTICS over 3.3V operating range

Symbol	Parameter	Conditions	Min	Max	Unit
VIH	Input HIGH Voltage		2.0		V
VIL	Input LOW Voltage			0.8	V
VOH	Output HIGH Voltage	IOH = -2.4 mA	2.4		V
		IOH = -10 μ A	VCC-0.1		V
VOL	Output LOW Voltage	IOL = 4 mA		0.4	V
		IOL = 10 μ A		0.1	V
IIH	Input High Current Sink (for tolerance to 5V devices)	5.5V > VI > VCC		12	mA
II	Input Leakage Current	VI = VCC or GND	-10	10	μ A
IOZ	3-State Output Leakage Current	VI = VCC or GND	-10	10	μ A
CI	Input Capacitance [5]			10	pF
IOS	Output Short Circuit Current [6]	VO = GND	-10	-70	mA
		VO = VCC	25	130	mA
ICC	D.C. Supply Current [7]	VI, VIO = VCC or GND	0.5 (typ)	3	mA

Notes:

[5] Capacitance is sample tested only.

[6] Only one output at a time. Duration should not exceed 30 seconds.

[7] For commercial grade devices only. Maximum ICC is 5 mA for all industrial grade devices. For AC conditions, contact QuickLogic customer engineering.



AC CHARACTERISTICS at VCC = 5V, TA = 25°C (K = 1.00)

Propagation delays depend on routing, fanout, load capacitance, supply voltage, junction temperature, and process variation. The AC Characteristics are a design guide to provide initial timing estimates at nominal conditions. Worst case estimates are obtained when nominal propagation delays are multiplied by the appropriate Delay Factor, K, as specified in the Delay Factor table (Operating Range). The QuickChip/QuickTools/QuickWorks software incorporates data sheet AC Characteristics into the design database for precise path analysis or simulation results following place and route.

Logic Cells

Symbol	Parameter	Propagation Delays (ns) Fanout [8]				
		1	2	3	4	8
tPD	Combinatorial Delay [9]	1.4	1.7	2.0	2.3	3.5
tSU	Setup Time [9]	1.8	1.8	1.8	1.8	1.8
tH	Hold Time	0.0	0.0	0.0	0.0	0.0
tCLK	Clock to Q Delay	0.8	1.1	1.4	1.7	2.9
tCWHI	Clock High Time	2.0	2.0	2.0	2.0	2.0
tCWLO	Clock Low Time	2.0	2.0	2.0	2.0	2.0
tSET	Set Delay	1.4	1.7	2.0	2.3	3.5
tRESET	Reset Delay	1.2	1.5	1.8	2.1	3.3
tSW	Set Width	1.9	1.9	1.9	1.9	1.9
tRW	Reset Width	1.8	1.8	1.8	1.8	1.8

Input-Only Cells

Symbol	Parameter	Propagation Delays (ns) Fanout [8]						
		1	2	3	4	8	12	24
tIN	High Drive Input Delay	2.5	2.6	2.6	2.7	3.5	4.6	5.8
tINI	High Drive Input, Inverting Delay	2.6	2.7	2.7	2.8	3.6	4.7	5.9
tISU	Input Register Set-Up Time	4.8	4.8	4.8	4.8	4.8	4.8	4.8
tIH	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0
tICLK	Input Register Clock To Q	0.9	1.0	1.0	1.1	1.9	3.0	4.2
tIRST	Input Register Reset Delay	0.8	0.9	0.9	1.0	1.8	2.9	4.1
tIESU	Input Register clock Enable Set-Up Time	4.1	4.1	4.1	4.1	4.1	4.1	4.1
tIEH	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0	0.0

Notes:

- [8] Stated timing for worst case Propagation Delay over process variation at VCC=5.0V and TA=25°C. Multiply by the appropriate Delay Factor, K, for speed grade, voltage and temperature settings as specified in the Operating Range.
- [9] These limits are derived from a representative selection of the slowest paths through the pASIC 2 logic cell *including typical net delays*. Worst case delay values for specific paths should be determined from timing analysis of your particular design.



Clock Cells

Symbol	Parameter	Propagation Delays (ns) Loads per Half Column [10]						
		1	2	3	4	8	10	13
tACK	Array Clock Delay	2.2	2.2	2.3	2.4	2.5	2.6	
tGCKP	Global Clock Pin Delay	1.2	1.2	1.2	1.2	1.2	1.2	1.2
tGCKB	Global Clock Buffer Delay	1.5	1.6	1.6	1.7	1.8	1.9	2.0

I/O Cells

Symbol	Parameter	Propagation Delays (ns) Fanout [8]					
		1	2	3	4	8	10
tI/O	Input Delay (bidirectional pad)	1.8	2.1	2.4	2.7	3.9	4.6
tISU	Input Register Set-Up Time	4.8	4.8	4.8	4.8	4.8	4.8
tIH	Input Register Hold Time	0.0	0.0	0.0	0.0	0.0	0.0
tIOCLK	Input Register Clock To Q	0.8	1.1	1.4	1.7	2.9	3.6
tIORST	Input Register Reset Delay	0.7	1.0	1.3	1.6	2.8	3.5
tIESU	Input Register clock Enable Set-Up Time	4.1	4.1	4.1	4.1	4.1	4.1
tIEH	Input Register Clock Enable Hold Time	0.0	0.0	0.0	0.0	0.0	0.0

Symbol	Parameter	Propagation Delays (ns) Output Load Capacitance (pF)				
		30	50	75	100	150
tOUTLH	Output Delay Low to High	2.6	3.0	3.6	4.1	5.2
tOUTH	Output Delay High to Low	2.8	3.3	3.9	4.5	5.7
tPZH	Output Delay Tri-state to High	2.1	2.6	3.1	3.7	4.8
tPZL	Output Delay Tri-state to Low	2.6	3.3	4.1	4.9	6.5
tPHZ	Output Delay High to Tri-State [11]	2.9				
tPLZ	Output Delay Low to Tri-State [11]	3.3				

Notes:

[10] The array distributed networks consist of 48 half columns and the global distributed networks consist of 52 half columns, each driven by an independent buffer. The number of half columns used does not affect clock buffer delay. The array clock has up to 10 loads per half column. The global clock has up to 13 loads per half column.

[11] The following loads are used for tPXZ:

